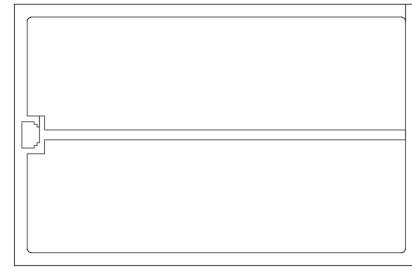


# MOSFET – Power, N-Channel, Automotive, SUPERFET® III, FRFET®

650 V, 40 mΩ

**NVCR8LS040N65S3FA**



## Features

- Typical  $R_{DS(on)} = 33.8 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$
- Typical  $Q_{g(tot)} = 153 \text{ nC}$  at  $V_{GS} = 10 \text{ V}$
- AEC-Q101 Qualified
- RoHS Compliant

## DIMENSION ( $\mu\text{m}$ )

Die Size	9510 x 6170
Die Size (Sawn)	9490 $\pm$ 30 x 6150 $\pm$ 30
Source Attach Area	(8835 x 2626.5) x 2
Gate Attach Area	406 x 618
Die Thickness	203.2 $\pm$ 25.4

Gate and Source : AlSiCu

Drain : Ti-NiV-Ag (back side of die)

Passivation : SiN

Wafer Diameter : 8 inch

Wafer sawn on UV Tape

Bad dice identified in Inking

Gross Die Count : 419

## ORDERING INFORMATION

Device	Package
NVCR8LS040N65S3FA	Wafer Sawn on Foil

## RECOMMENDED STORAGE CONDITIONS

Temperature	22 to 28°C
RH	40% to 66%

## ELECTRICAL CHARACTERISTICS

The Chip is 100% Probed to Meet the Conditions and Limits Specified at  $T_J = 25^\circ\text{C}$

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}$ , $V_{GS} = 0 \text{ V}$	650	–	–	V
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS} = 650 \text{ V}$ , $V_{GS} = 0 \text{ V}$	–	–	10	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	–	–	$\pm 100$	nA
$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 2.1 \text{ mA}$	3.0	–	5.0	V
$*R_{DS(on)}$	Bare Die Drain to Source On Resistance	$I_D = 32.5 \text{ A}$ , $V_{GS} = 10 \text{ V}$	–	33.8	40	$\text{m}\Omega$
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 32.5 \text{ V}$			1.2	V

\*Accurate  $R_{DS(on)}$  test at die level is not feasible for this thin die as limited by the test contact precision attainable in a die form. The max  $R_{DS(on)}$  specification is defined from the historical performance of the die in package but is not guaranteed by test in production. The die  $R_{DS(on)}$  performance depends on the Source wire/ribbon bonding layout.

# NVCR8LS040N65S3FA

## ABSOLUTE MAXIMUM RATINGS

in Reference to the NVHL040N65S3F electrical data in TO-247 (  $T_J = 25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter		Ratings	Unit
$V_{DSS}$	Drain to Source Voltage		650	V
$V_{GS}$	Gate to Source Voltage	DC	$\pm 30$	V
		AC ( $f > 1\text{ Hz}$ )	$\pm 30$	V
$I_D$	Continuous Drain Current	$T_C = 25^{\circ}\text{C}$	65	A
		$T_C = 100^{\circ}\text{C}$	45	A
$I_{DM}$	Pulsed Drain Current	Pulsed (Note 1)	162.5	A
$E_{AS}$	Single Pulse Avalanche Energy (Note 2)		1009	mJ
$E_{AR}$	Repetitive Avalanche (Note 1)		4.46	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		50	V/ns
$P_D$	Power Dissipation $R_{\theta JC}$	$T_C = 25^{\circ}\text{C}$	446	W
$T_J, T_{STG}$	Operating and Storage Temperature		-55 to +150	$^{\circ}\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature.

2.  $I_{AS} = 9\text{ A}$ ,  $R_G = 25\ \Omega$ , Starting  $T_J = 25^{\circ}\text{C}$ .

3.  $I_{SD} < 32.5\text{ A}$ ,  $di/dt \leq 200\text{ A/ms}$ ,  $V_{DD} \leq BVDSS$ , starting  $T_J = 25^{\circ}\text{C}$

## THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.28	$^{\circ}\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max	40	$^{\circ}\text{C/W}$

# NVCR8LS040N65S3FA

## ELECTRICAL CHARACTERISTICS

in Reference to the NVHL040N65S3F electrical data in TO-247-3LD (  $T_J = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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### OFF CHARACTERISTICS

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 1\text{ mA}, V_{GS} = 0\text{ V}$	650	–	–	V
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}, T_J = 25^\circ\text{C}$	–	–	10	$\mu\text{A}$
		$V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$	–	103	–	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 30\text{ V}$	–	–	$\pm 100$	nA

### ON CHARACTERISTICS

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.1\text{ mA}$	3.0	–	5.0	V
$R_{DS(on)}$	Drain to Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 32.5\text{ A}$	–	33.8	40	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 32.5\text{ A}$		40		S

### DYNAMIC CHARACTERISTICS

$C_{iss}$	Input Capacitance	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$	–	5875	–	pF
$C_{oss}$	Output Capacitance		–	140	–	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$		1333		pF
$C_{oss(er.)}$	Energy Related Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$		241		pF
$Q_{g(ToT)}$	Total Gate Charge	$V_{GS} = 10\text{ V}, V_{DS} = 400\text{ V}, I_D = 32.5\text{ A}$ (Note 4)	–	153	–	nC
$Q_{gs}$	Gate to Source Gate Charge		–	51	–	nC
$Q_{gd}$	Gate to Drain “Miller” Charge		–	61	–	nC
ESR	Equivalent Series Resistance	$f = 1\text{ MHz}$	–	1.9	–	$\Omega$

### SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400\text{ V}, I_D = 32.5\text{ A}, V_{GS} = 10\text{ V},$ $R_G = 2.2\text{ }\Omega$ (Note 4)	–	41	–	ns
$t_r$	Rise Time		–	53	–	ns
$t_{d(off)}$	Turn-Off Delay Time		–	96	–	ns
$t_f$	Fall Time		–	28	–	ns

### DRAIN – SOURCE DIODE CHARACTERISTICS

$I_S$	Maximum Continuous Drain to Source Diode Forward Current				65	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current				162.5	A
$V_{SD}$	Source to Drain Diode Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 32.5\text{ A}, V_{GS} = 0\text{ V}$	–	–	1.3	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 32.5\text{ A},$ $di_{SD}/dt = 100\text{ A}/\mu\text{s}$	–	159	–	ns
$Q_{rr}$	Reverse Recovery Charge		–	840	–	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS

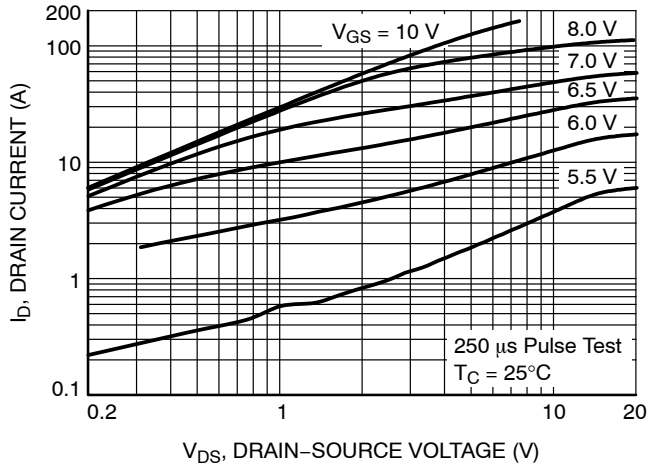


Figure 1. On-Region Characteristics

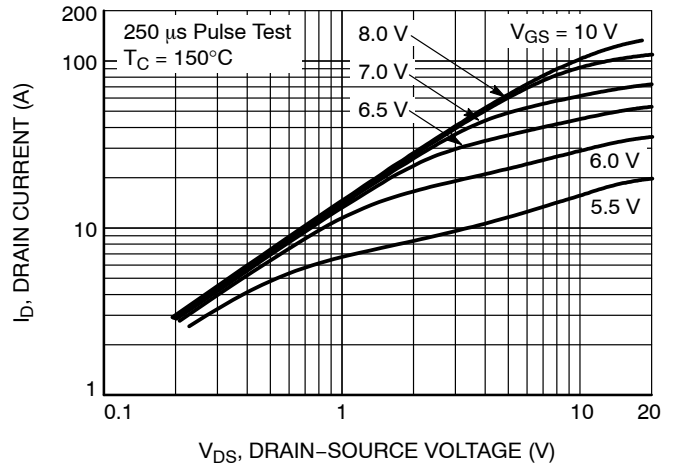


Figure 2. On-Region Characteristics

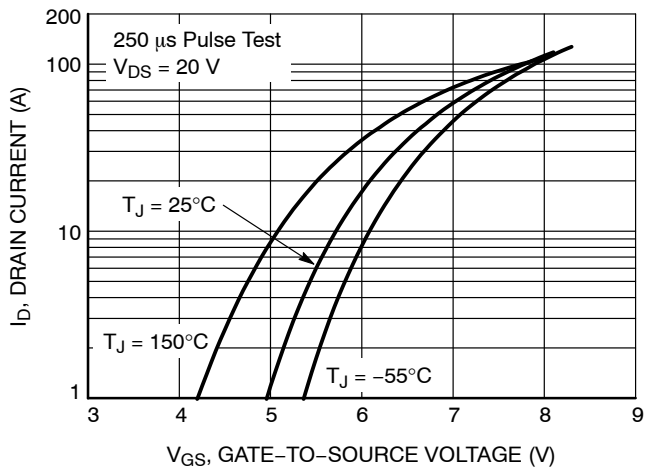


Figure 3. Transfer Characteristics

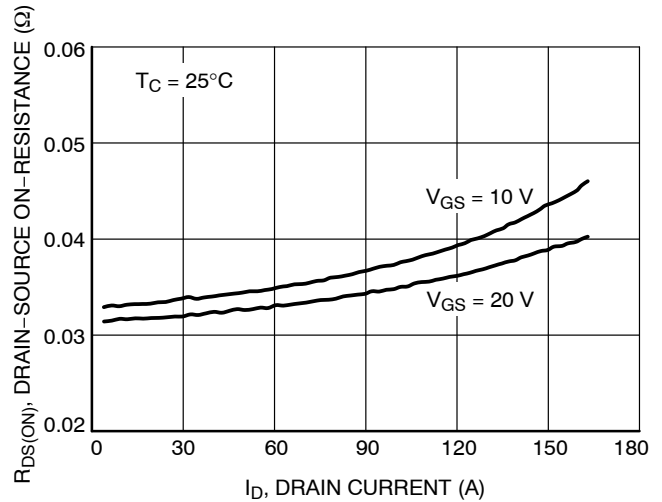


Figure 4. On-Resistance Variation vs. Drain Current and Gate Voltage

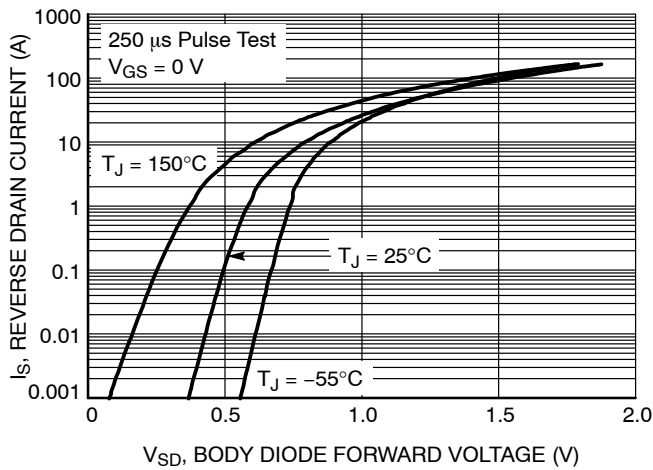


Figure 5. Body Diode Forward Voltage Variation vs. Source Current and Temperature

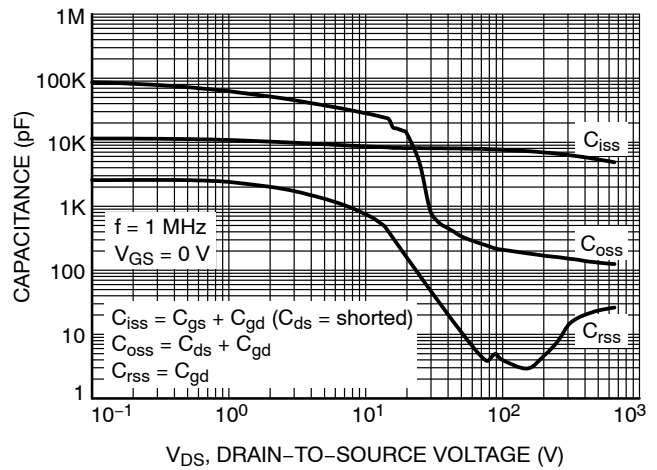


Figure 6. Capacitance Characteristics

TYPICAL CHARACTERISTICS

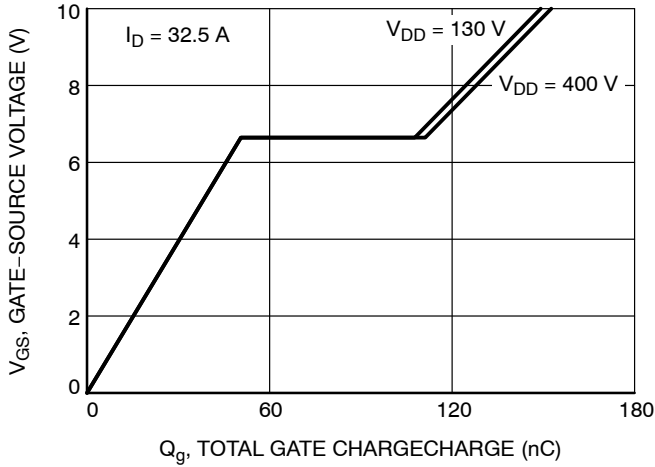


Figure 7. Gate Charge Characteristics

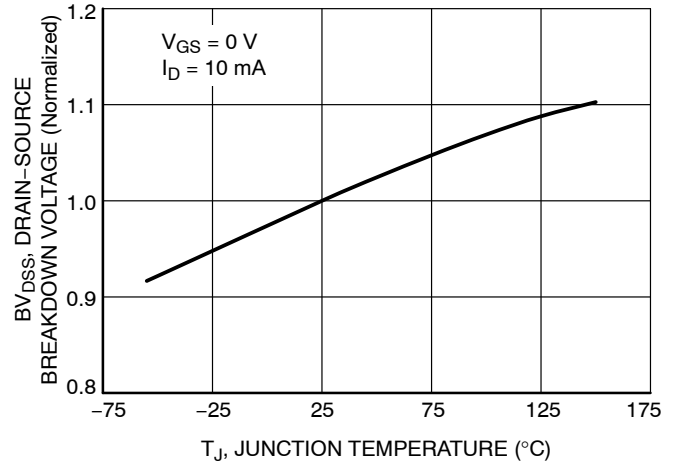


Figure 8. Breakdown Voltage Variation vs. Temperature

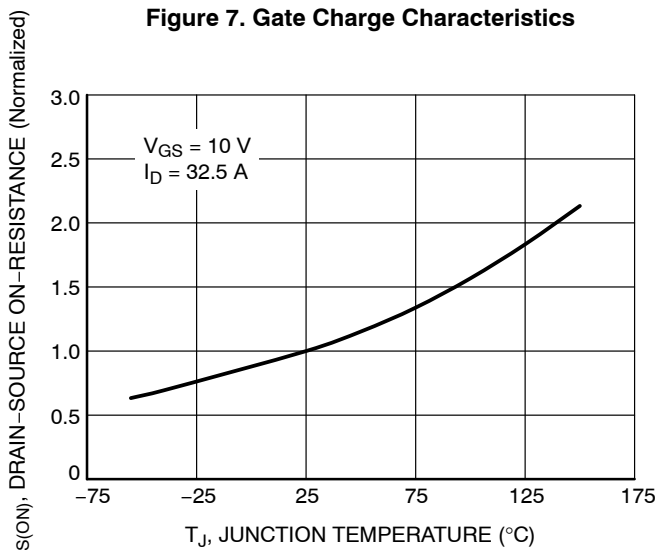


Figure 9. On-Resistance Variation vs. Temperature

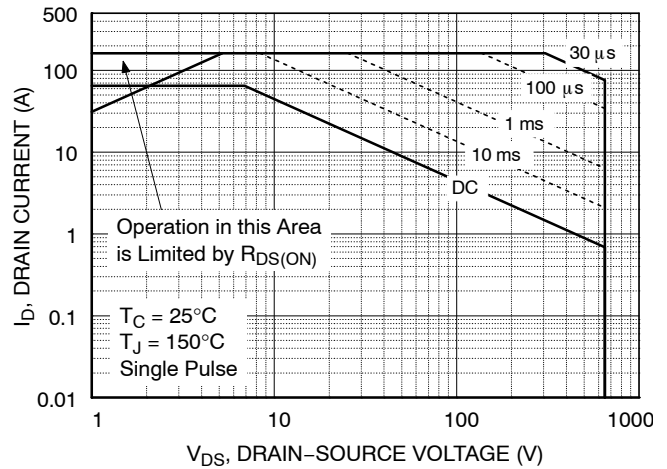


Figure 10. Maximum Safe Operating Area

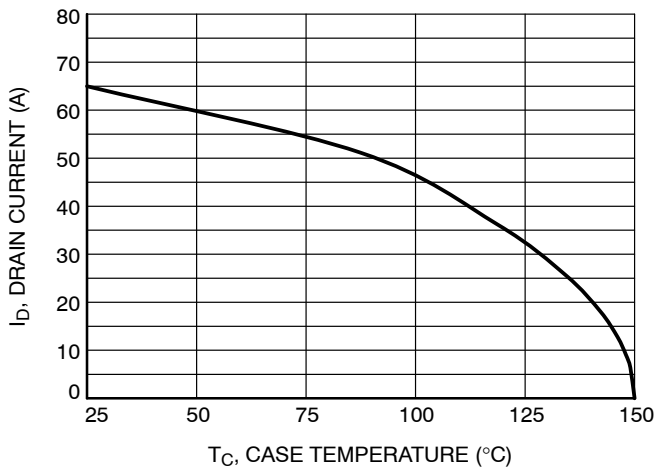


Figure 11. Maximum Drain Current vs. Case Temperature

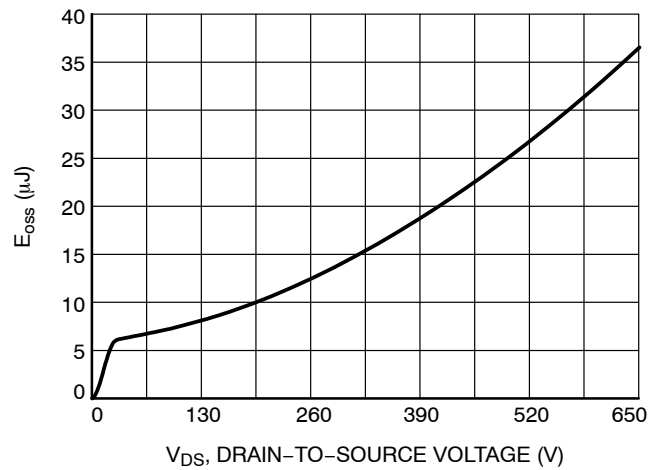
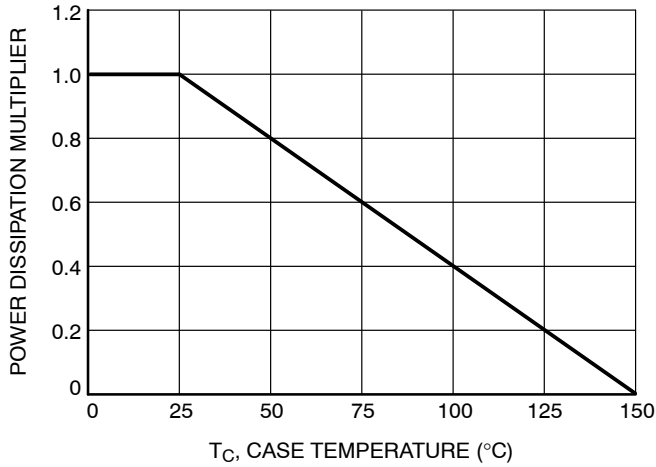


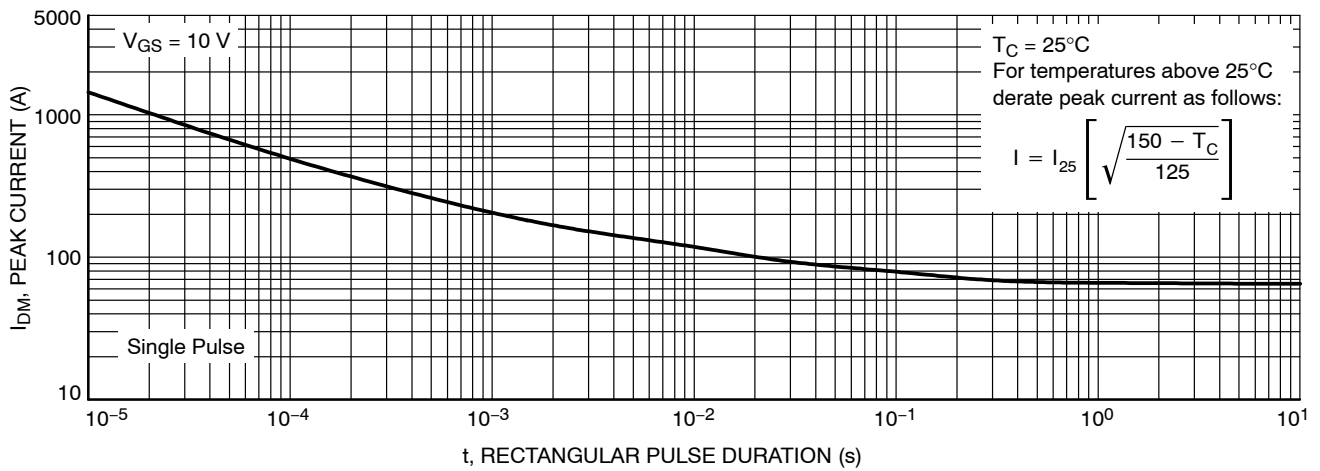
Figure 12.  $E_{OSS}$  vs. Drain-to-Source Voltage

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## TYPICAL CHARACTERISTICS

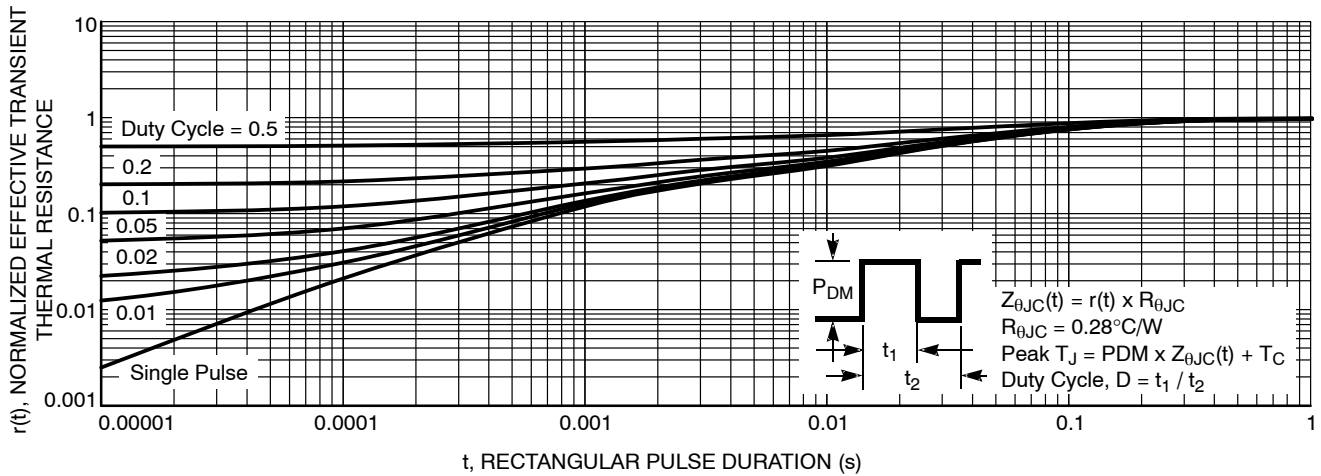
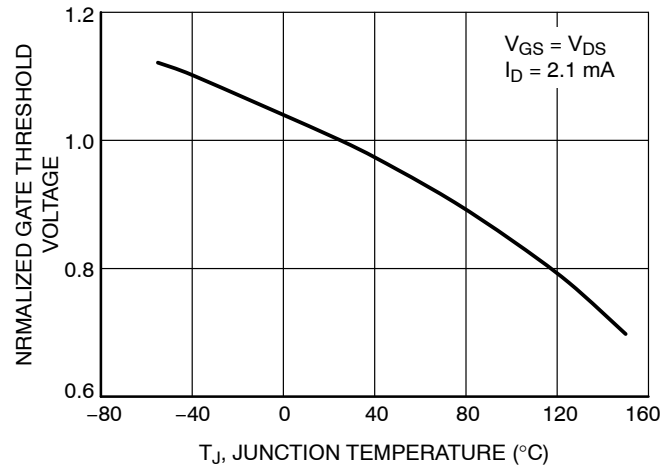
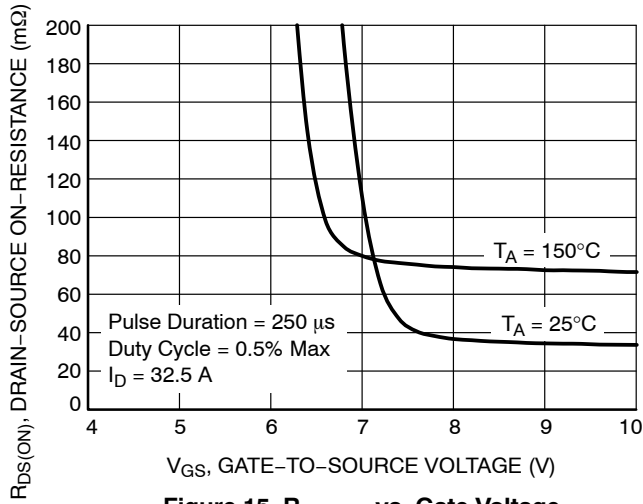


**Figure 13. Normalized Power Dissipation vs. Case Temperature**



**Figure 14. Peak Current Capability**

TYPICAL CHARACTERISTICS



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